



Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model

[List multiple models if applicable.]

HP Beats Special Edition 15 Notebook PC

HP Beats 15 Notebook PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	

Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	#1
Description #2	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery module
2. Remove base rubber foot -L & -R
3. Dis-fasten Base Cap -L & -R screw*2
4. Remove Base Cap foot -L & -R
5. Dis-fasten ODD screw*1
6. Remove ODD
7. Dis-fasten BASE screw*18
8. Pull out FFC*3 (Power, Touchpad, keyboard membrane)
9. Dis-fasten daughter boards screw*4 (Power, Touchpad)
10. Remove daughter boards*2 (Power, Touchpad)
11. Pull out wire cable *5(LCD, DC cable, HDD, ODD, speaker) Pull out FFC(USB, Battery)
12. Pull out Antenna cables
13. Dis-fasten Wireless screw*1
14. Remove Wireless card
15. Remove HDD
16. Dis-fasten USB boards screw*1
17. Remove USB boards
18. Dis-fasten motherboard screw*7
19. Remove motherboard
20. Remove Memory
21. Pull out fan cable
22. Dis-fasten Fan screws*1
23. Remove Fan
24. Dis-fasten thermal module screw*4
25. Remove thermal module
26. Remove ODD cable
27. Dis-fasten Battery boards screw*2
28. Remove Battery boards
29. Dis-fasten speaker screw*2
30. Remove speaker -L & -R
31. Dis-fasten Hinge screw*7
32. Remove DC cable
33. Dis-fasten LCD Bezel screws*2
34. Remove LCD bezel

35. Dis-fasten Hinge screw*6
36. Pull out LCD cable & camera cable
37. Remove LCD module
38. Remove Camera module
39. Remove LCD cable & camera cable & Antenna cables
40. Dis-fasten Hinge screw*6
41. Remove Hinge -L & -R

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly



3.22 Remove battery module



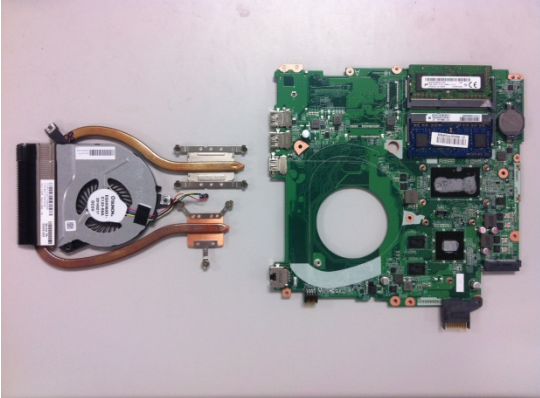
3.23 LCD module set disassembly



3.24 Top case disassembly



3.25 Thermal module and mother board disassembly



3.26 Bottom case disassembly

